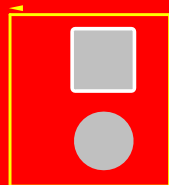


PMP30089

Rev. 1.0



VIN
GND



J2



TP3



TP1



TP7



J4



TP5



TP11

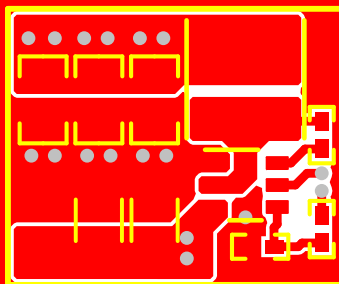


J6

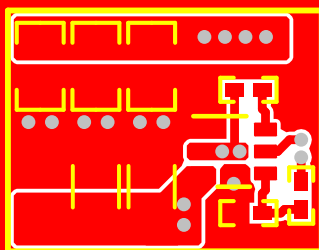


TP9

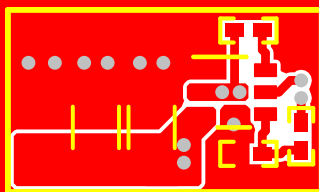
173mm²



141mm²

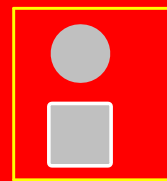


105mm²



TP4

GND
VOUT

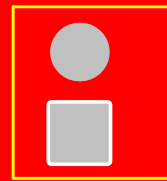


TP2



TP8

GND
VOUT

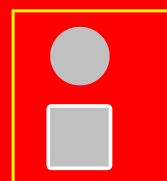


TP6

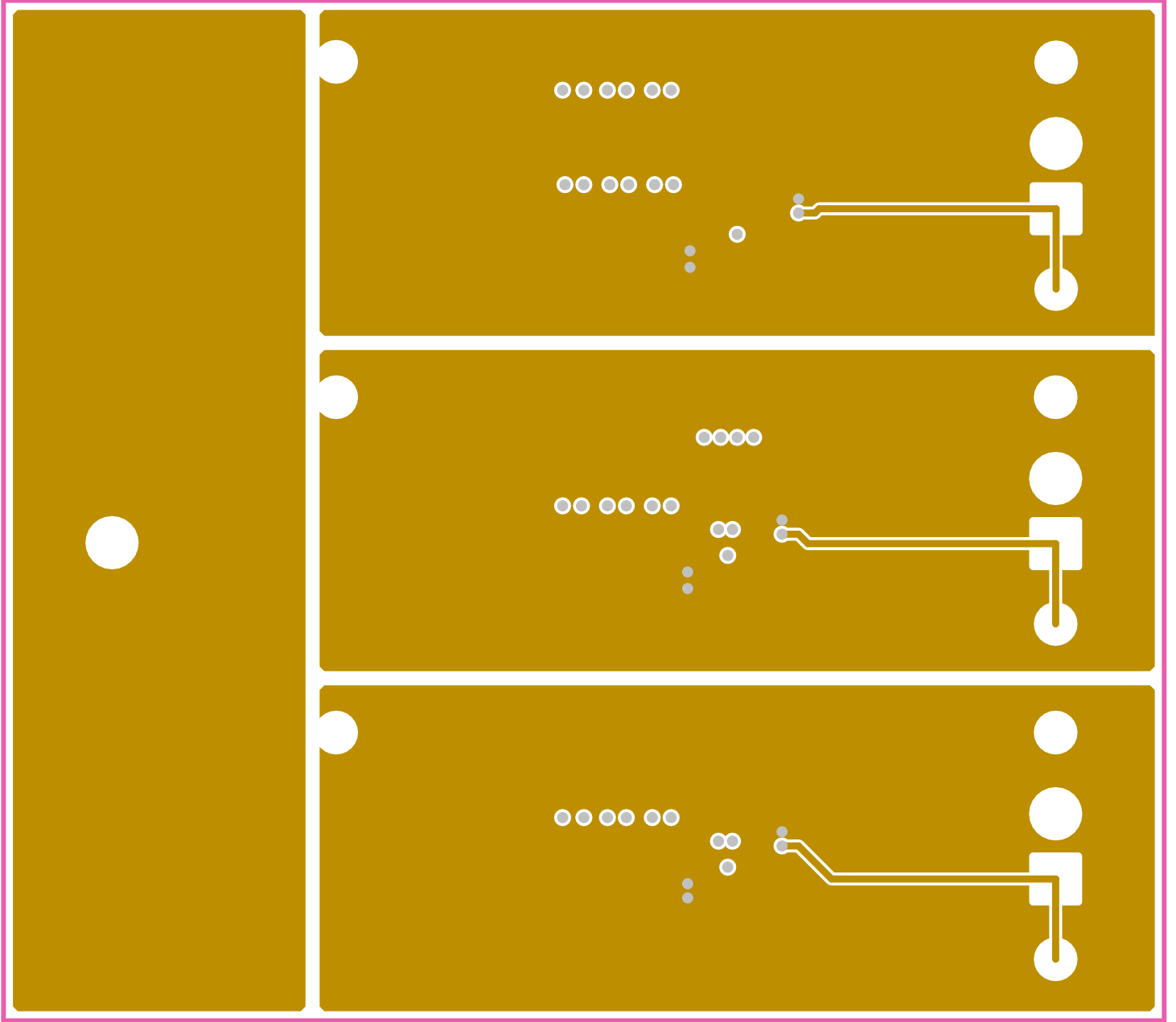


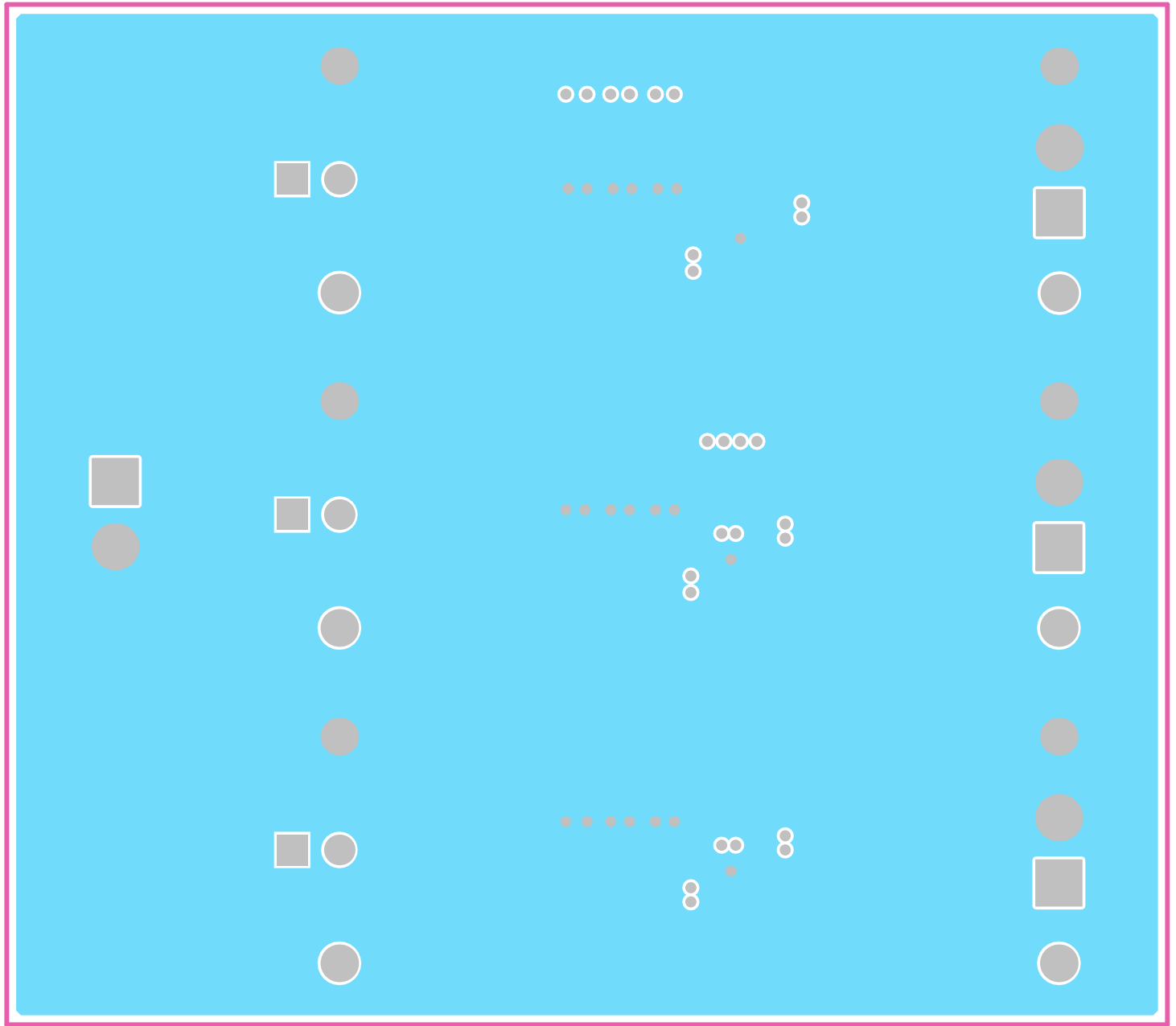
TP12

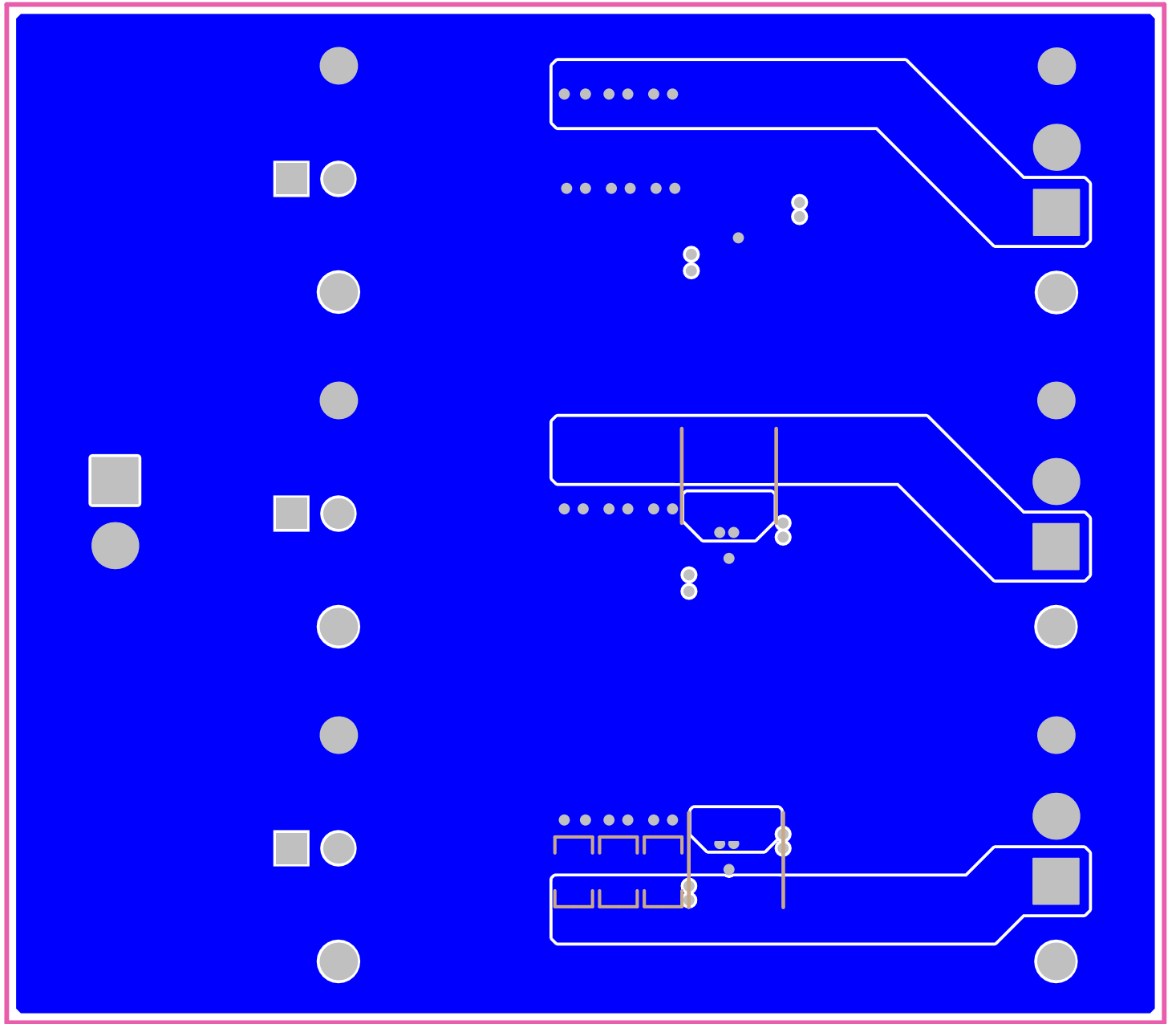
GND
VOUT



TP10







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